



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-24
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IYWY*0507AT6	A	ZS1A	2014-07-24
Amount	UoM	Unit type	ST ECOPACK Grade	
17.10	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.8X1.5X0.9	5	gull wing	
Comment	SOT 23-5; MD valid for CP: TS507ILT.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IYWY*0507AT6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	0.873	mg	supplier	Silicon die	Silicon (Si)	7440-21-3		0.868	mg	975281	50760
Silicon die			mg	supplier	Alloy	Aluminium (Al)	7429-90-5		0.003	mg	3371	175
Silicon die			mg	supplier	Alloy	Titanium (Ti)	7440-32-6		0.001	mg	1124	58
Silicon die			mg	supplier	Alloy	Titanium Nitride (TiN)	25583-20-4		0.001	mg	1124	58
Silicon die	Copper and its alloy	0.017	mg	supplier	ALLOY	Silicon Nitride (SiN)	68034-42-4		0.002	mg	2247	117
Silicon die			mg	supplier	ALLOY	Silicon Oxide(SiO2)	7631-86-9		0.008	mg	8989	468
Silicon die			mg	supplier	ALLOY	Gamma-butyrolactone	96-48-0		0.005	mg	5618	292
Silicon die			mg	supplier	ALLOY	Polyhydroxyamide	55295-98-2		0.002	mg	2247	117
Leadframe	Copper and its alloy	7.192	mg	Supplier	Alloy	Copper	7440-50-8		6.928	mg	963293	405146
Leadframe			mg	Supplier	Alloy	Iron	7439-89-6		0.162	mg	22525	9474
Leadframe			mg	Supplier	Alloy	Iron Phosphide (Fe2P)	1310-43-6		0.002	mg	278	117
Leadframe			mg	Supplier	Alloy	Zinc	7440-66-6		0.009	mg	1251	526
Leadframe			mg	Supplier	Alloy	Nickel	7440-02-0		0.083	mg	11541	4854
Leadframe			mg	Supplier	Alloy	Palladium	7440-05-3		0.007	mg	973	409
Leadframe			mg	Supplier	Alloy	Gold	7440-57-5		0.001	mg	139	58
Die Attach	Other Organic Material	0.069	mg	Supplier	Glue	Silver	7440-22-4		0.056	mg	811594	3275
Die Attach			mg	Supplier	Glue	Carbocyclic Acrylates	proprietary		0.007	mg	101449	409
Die Attach			mg	Supplier	Glue	Bismaleimide resin	proprietary		0.002	mg	28986	117
Die Attach			mg	Supplier	Glue	2-preponoic acid, 2-methy	68586-19-6		0.002	mg	28986	117
Die Attach			mg	Supplier	Glue	Additive	Proprietary		0.002	mg	28986	117
Bonding Wire	Other Inorganic Material	0.15	mg	Supplier	Bonding Wire	Au	7440-57-5		0.15	mg	1000000	8772
Encapsulation	Other Organic Material	8.799	mg	Supplier	Molding Compound	Epoxy Resin-1	Proprietary		0.176	mg	20002	10292
Encapsulation			mg	Supplier	Molding Compound	Epoxy Resin-2	Proprietary		0.176	mg	20002	10292
Encapsulation			mg	Supplier	Molding Compound	Epoxy Resin-3	Proprietary		0.176	mg	20002	10292
Encapsulation			mg	Supplier	Molding Compound	Phenol resin	Proprietary		0.352	mg	40005	20585
Encapsulation			mg	Supplier	Molding Compound	Silica	60676-86-0		7.637	mg	867940	446608
Encapsulation			mg	Supplier	Molding Compound	Carbon Black	1333-86-4		0.018	mg	2046	1053
Encapsulation			mg	Supplier	Molding Compound	Others	Proprietary		0.264	mg	30003	15439
										mg		